Hot Melt Adhesive Application System
MX 4003

The compact and easy to use system package for electro component moulding applications.

The MX 4003 hot melt adhesive application system was especially designed to process copolyamides for moulding electric and electronic components like sensors, relays, switches, plugs and connectors. The compact size allows easy integration of the unit into moulding workstations. All controls are easily accessible from the front of the unit, giving the operator complete process control of all important parameters like temperatures or max. material pressure.

The system is based on the industry proven MX hot melt adhesive applicator series and includes all features needed for the easy and cost efficient moulding of components with high, reproduceable quality.

Features and Benefits

- Tank with low and high melt zone for processing heat sensitive materials under perfect conditions.
- Precision gear pump for exact metering of the material.
- Maintenance-free AC drive.
- Pneumatic bypass for discrete control of the max. material pressure.
- Four self optimizing, microprocessor based PID temperature controllers with digital display of setpoints and actual values for precise temperature control ensuring consistent high moulding quality.
- Durable non-stick coating of the tank for easy cleaning.
- Easy to change filter cartridge for clean moulding material without contamination.

Technical Specification

- Tank capacity: 2.3 kg (5 lbs.)
- Melt rate: up to 3 kg/h (6.6 lbs./h)
- Pump rate: max. 270 g/min. (0.6 lbs/min.)
- Temperature range: 50 - 250 °C (122 - 480 °F)
- Electrical service: 230 V AC 50/60 Hz, 1 ph
- Power consumption: hot melt applicator: 2000 W
  heated hose: max. 1200 W
  application head: max. 1200 W
- System pressure: 5 - 60 bar (71 - 853 psi)
  max. pressure, pneumatically adjustable
- Dimensions: 950 x 400 x 575 mm
  (37.4 x 15.7 x 22.6 in.)